

## LISTING OF THE CLAIMS

No amendments are made to the claims. This listing of pending claims is provided for convenience:

1. (Cancelled)

2. (Previously presented): A computer-implemented method for generating a work-in-progress (WIP) tracking report for the manufacture of a semiconductor part for a customer, the WIP tracking report reflecting a progress of WIP for the semiconductor part through a semiconductor supply chain of vendors, the method comprising the steps of:

receiving via a communications network one or more raw WIP updates from one or more vendors in the semiconductor supply chain;

updating a database representation of the semiconductor supply chain to reflect the received raw WIP updates;

generating by computer a WIP tracking report from the database representation of the semiconductor supply chain; and

making the WIP tracking report available to the customer.

3. (Previously presented): The computer-implemented method of claim 2 wherein the WIP tracking report shows a volume of WIP at different stages of the semiconductor supply chain, and the volume of WIP at one or more of the stages is measured in expected good parts.

4. (Previously presented): The computer-implemented method of claim 3 wherein:

the raw WIP updates received from the vendors show a volume of WIP at different steps within a vendor's process;

the different steps within a vendor's process are mapped to stages for the WIP tracking report; and

the volume of WIP at different steps within a vendor's process are converted to volume of WIP at different stages in the WIP tracking report.

5. (Previously presented): The computer-implemented method of claim 4 wherein a volume of WIP at one or more stages in the WIP tracking report reflect a volume of WIP aggregated over multiple vendors.
6. (Previously presented): The computer-implemented method of claim 2 wherein the WIP tracking report shows a volume of expected good parts to be delivered to the customer on certain delivery dates.
7. (Previously presented): The computer-implemented method of claim 6 wherein the WIP tracking report shows, for the delivery dates, a volume of requested good parts, a volume of committed good parts and a volume of shipped/projected good parts, where volumes are measured in expected good parts.
8. (Previously presented): The computer-implemented method of claim 6 wherein the volume of expected good parts to be delivered to the customer on the delivery dates is estimated based on statistical modeling of the semiconductor supply chain.
9. (Previously presented): The computer-implemented method of claim 2 wherein the WIP tracking report shows a status of one or more orders of the semiconductor part and volumes are measured in expected good parts.
10. (Previously presented): The computer-implemented method of claim 9 wherein the orders include possible statuses of backlogged, WIP and shipped.
11. (Previously presented): The computer-implemented method of claim 2 further comprising:  
generating by computer a chart of delivery performance for at least one vendor, the chart  
generated from the database representation of the semiconductor supply chain.
12. (Previously presented): The computer-implemented method of claim 2 wherein the WIP tracking report is pre-defined and not defined by the customer.
13. (Previously presented): The computer-implemented method of claim 2 further comprising:  
generating by computer an internal WIP tracking report from the database representation  
of the semiconductor supply chain, for a fabless semiconductor provider's internal  
use.

14. (Previously presented): The computer-implemented method of claim 13 wherein volumes reported in the internal WIP tracking report can be different than volumes reported in the WIP tracking report made available to the customer.

15. (Previously presented): The computer-implemented method of claim 13 wherein the WIP tracking report made available to the customer reduces bad news compared to the internal WIP tracking report.

16. (Previously presented): The computer-implemented method of claim 2 wherein the WIP tracking report is made available to the customer by a secure access method.

17. (Previously presented): The computer-implemented method of claim 2 wherein the WIP tracking report is made available to the customer by at least one of Internet access, email delivery, and facsimile.

18. (Previously presented): The computer-implemented method of claim 2 wherein WIP volumes are converted to expected good parts based on statistical modeling of the semiconductor supply chain.

19. (Previously presented): The computer-implemented method of claim 2 wherein the step of updating a database representation of the semiconductor supply chain comprises:

consistency checking the received raw WIP updates; and

updating the database representation of the semiconductor supply chain according to received raw WIP updates that have passed the consistency check.

20. (Previously presented): The computer-implemented method of claim 19 wherein the step of updating a database representation of the semiconductor supply chain further comprises:

upon detection of inconsistency in a received raw WIP update, notifying the vendor of the inconsistency.

21. (Previously presented): The computer-implemented method of claim 2 further comprising the step of:

detecting significant deviation between scheduled delivery of the semiconductor parts and estimated delivery of the semiconductor parts according to the WIP tracking report.

22. (Previously presented): The computer-implemented method of claim 21 further comprising the step of:

notifying at least one of a customer, a fabless semiconductor provider and a vendor of the detected deviation.

23. (Previously presented): The computer-implemented method of claim 2 wherein at least one volume of WIP in the WIP tracking report is measured in expected good parts.

24. (Previously presented): A work-in-progress (WIP) reporting system for generating a WIP tracking report for the manufacture of a semiconductor part, the WIP tracking report reflecting a progress of WIP for the semiconductor part through a semiconductor supply chain of vendors, the WIP reporting system comprising:

a WIP database containing a database representation of the semiconductor supply chain;  
a revision engine coupled to the WIP database for updating the database representation of the semiconductor supply chain to reflect raw WIP updates received from one or more vendors via a communications network; and  
a presentation engine coupled to the WIP database for generating a WIP tracking report.

25. (Previously presented): The WIP reporting system of claim 24 wherein the WIP tracking report shows a volume of WIP at different stages of the semiconductor supply chain, and the volume of WIP at one or more of the stages is measured in expected good parts.

26. (Previously presented): The WIP reporting system of claim 25 wherein:

the raw WIP updates received from the vendors show a volume of WIP at different steps within a vendor's process;  
the different steps within a vendor's process are mapped to stages for the WIP tracking report; and

the volume of WIP at different steps within a vendor's process are converted to volume of WIP at different stages in the WIP tracking report.

27. (Previously presented): The WIP reporting system of claim 26 wherein a volume of WIP at one or more stages in the WIP tracking report reflect a volume of WIP aggregated over multiple vendors.
28. (Previously presented): The WIP reporting system of claim 24 wherein the WIP tracking report shows a volume of expected good parts to be delivered on certain delivery dates.
29. (Previously presented): The WIP reporting system of claim 28 wherein the WIP tracking report shows, for the delivery dates, a volume of requested good parts, a volume of committed good parts and a volume of shipped/projected good parts, where volumes are measured in expected good parts.
30. (Previously presented): The WIP reporting system of claim 28 wherein the volume of expected good parts to be delivered on the delivery dates is estimated based on statistical modeling of the semiconductor supply chain.
31. (Previously presented): The WIP reporting system of claim 24 wherein the WIP tracking report shows a status of one or more orders of the semiconductor part and volumes are measured in expected good parts.
32. (Previously presented): The WIP reporting system of claim 31 wherein the orders include possible statuses of backlogged, WIP and shipped.
33. (Previously presented): The WIP reporting system of claim 24 wherein the presentation engine is further for generating a chart of delivery performance for at least one vendor, the chart generated from the database representation of the semiconductor supply chain.
34. (Previously presented): The WIP reporting system of claim 24 wherein the WIP tracking report is pre-defined.
35. (Previously presented): The WIP reporting system of claim 24 wherein the presentation engine comprises:

a customer presentation engine for generating an external WIP tracking report from the database representation of the semiconductor supply chain, for use by a customer; and

an internal presentation engine for generating an internal WIP tracking report from the database representation of the semiconductor supply chain, for internal use by a fabless semiconductor provider.

36. (Previously presented): The WIP reporting system of claim 35 wherein volumes reported in the internal WIP tracking report can be different than volumes reported in the external WIP tracking report.

37. (Previously presented): The WIP reporting system of claim 35 wherein the external WIP tracking report reduces bad news compared to the internal WIP tracking report.

38. (Previously presented): The WIP reporting system of claim 24 further comprising:  
a customer interface for making the WIP tracking report available to the customer by a secure access method.

39. (Previously presented): The WIP reporting system of claim 24 further comprising:  
a customer interface for making the WIP tracking report available to the customer by at least one of Internet access, email delivery, and facsimile.

40. (Previously presented): The WIP reporting system of claim 24 wherein WIP volumes are converted to expected good parts based on statistical modeling of the semiconductor supply chain.

41. (Previously presented): The WIP reporting system of claim 24 further comprising:  
a WIP consistency checking module coupled to the WIP database for consistency checking the received raw WIP updates, wherein the revision engine updates the database representation of the semiconductor supply chain according to received raw WIP updates that have passed the consistency check.

42. (Previously presented): The WIP reporting system of claim 41 wherein, upon detection of inconsistency in a received raw WIP update, the vendor is notified of the inconsistency.

43. (Previously presented): The WIP reporting system of claim 24 further comprising:  
an alerts engine coupled to the WIP database for detecting significant deviation between  
scheduled delivery of the semiconductor parts and estimated delivery of the  
semiconductor parts according to the WIP tracking report.
44. (Previously presented): The WIP reporting system of claim 43 wherein the alerts engine is  
further for notifying at least one of a customer, a fabless semiconductor provider and a vendor of  
the detected deviation.
45. (Previously presented): The WIP reporting system of claim 24 wherein at least one volume  
of WIP in the WIP tracking report is measured in expected good parts.
46. (Previously presented): A computer readable medium containing software for generating a  
work-in-progress (WIP) tracking report for the manufacture of a semiconductor part for a  
customer, the WIP tracking report reflecting a progress of WIP for the semiconductor part  
through a semiconductor supply chain of vendors, the software for causing a compute facility to  
execute the steps of:  
receiving via a communications network one or more raw WIP updates from one or more  
vendors in the semiconductor supply chain;  
updating a database representation of the semiconductor supply chain to reflect the  
received raw WIP updates;  
generating a WIP tracking report from the database representation of the semiconductor  
supply chain; and  
making the WIP tracking report available to the customer.
47. (Previously presented): The computer readable medium of claim 46 wherein the WIP  
tracking report shows a volume of WIP at different stages of the semiconductor supply chain, and  
the volume of WIP at one or more of the stages is measured in expected good parts.
48. (Previously presented): The computer readable medium of claim 47 wherein:  
the raw WIP updates received from the vendors show a volume of WIP at different steps  
within a vendor's process;

the different steps within a vendor's process are mapped to stages for the WIP tracking report; and

the volume of WIP at different steps within a vendor's process are converted to volume of WIP at different stages in the WIP tracking report.

49. (Previously presented): The computer readable medium of claim 48 wherein a volume of WIP at one or more stages in the WIP tracking report reflect a volume of WIP aggregated over multiple vendors.

50. (Previously presented): The computer readable medium of claim 46 wherein the WIP tracking report shows a volume of expected good parts to be delivered to the customer on certain delivery dates.

51. (Previously presented): The computer readable medium of claim 50 wherein the WIP tracking report shows, for the delivery dates, a volume of requested good parts, a volume of committed good parts and a volume of shipped/projected good parts, where volumes are measured in expected good parts.

52. (Previously presented): The computer readable medium of claim 50 wherein the volume of expected good parts to be delivered to the customer on the delivery dates is estimated based on statistical modeling of the semiconductor supply chain.

53. (Previously presented): The computer readable medium of claim 46 wherein the WIP tracking report shows a status of one or more orders of the semiconductor part and volumes are measured in expected good parts.

54. (Previously presented): The computer readable medium of claim 53 wherein the orders include possible statuses of backlogged, WIP and shipped.

55. (Previously presented): The computer readable medium of claim 46 wherein the software further causes the compute facility to execute the step of:

generating a chart of delivery performance for at least one vendor, the chart generated from the database representation of the semiconductor supply chain.



56. (Previously presented): The computer readable medium of claim 46 wherein the WIP tracking report is pre-defined.

57. (Previously presented): The computer readable medium of claim 46 wherein the software further causes the compute facility to execute the step of:

generating by computer an internal WIP tracking report from the database representation of the semiconductor supply chain, for a fabless semiconductor provider's internal use.

58. (Previously presented): The computer readable medium of claim 57 wherein volumes reported in the internal WIP tracking report can be different than volumes reported in the WIP tracking report made available to the customer.

59. (Previously presented): The computer readable medium of claim 57 wherein the WIP tracking report made available to the customer reduces bad news compared to the internal WIP tracking report.

60. (Previously presented): The computer readable medium of claim 46 wherein the WIP tracking report is made available to the customer by a secure access method.

61. (Previously presented): The computer readable medium of claim 46 wherein the WIP tracking report is made available to the customer by at least one of Internet access, email delivery, and facsimile.

62. (Previously presented): The computer readable medium of claim 46 wherein WIP volumes are converted to expected good parts based on statistical modeling of the semiconductor supply chain.

63. (Previously presented): The computer readable medium of claim 46 wherein the step of updating a database representation of the semiconductor supply chain comprises:

consistency checking the received raw WIP updates; and

updating the database representation of the semiconductor supply chain according to received raw WIP updates that have passed the consistency check.

64. (Previously presented): The computer readable medium of claim 63 wherein the step of updating a database representation of the semiconductor supply chain further comprises:

upon detection of inconsistency in a received raw WIP update, notifying the vendor of the inconsistency.

65. (Previously presented): The computer readable medium of claim 46 wherein the software further causes the compute facility to execute the step of:

detecting significant deviation between scheduled delivery of the semiconductor parts and estimated delivery of the semiconductor parts according to the WIP tracking report.

66. (Previously presented): The computer readable medium of claim 65 wherein the software further causes the compute facility to execute the step of:

notifying at least one of a customer, a fabless semiconductor provider and a vendor of the detected deviation.

67. (Previously presented): The computer readable medium of claim 46 wherein at least one volume of WIP in the WIP tracking report is measured in expected good parts.

68. (Previously presented): A work-in-progress (WIP) reporting system for generating a WIP tracking report for the manufacture of a semiconductor part, the WIP tracking report reflecting a progress of WIP for the semiconductor part through a semiconductor supply chain of vendors, the WIP reporting system comprising:

means for receiving via a communications network one or more raw WIP updates from one or more vendors in the semiconductor supply chain;

means for updating a database representation of the semiconductor supply chain to reflect the received raw WIP updates;

means for generating by computer a WIP tracking report from the database representation of the semiconductor supply chain; and

means for making the WIP tracking report available to the customer.